

What is claimed is:

1. An embedding resin comprising a thermoplastic resin, an acid anhydride curing agent, a curing accelerator, and a filler, wherein the embedding resin shows a viscosity
5 of not higher than $85 \text{ Pa} \cdot \text{s}$ in a shear rate of 8.4 s^{-1} after allowing to stand for 24 hours at $25^\circ\text{C} \pm 1^\circ\text{C}$.

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2. The embedding resin according to claim 1, wherein the acid anhydride curing agent has a viscosity at $25^\circ\text{C} \pm 1^\circ\text{C}$ of not higher than $170 \text{ mPa} \cdot \text{s}$.

3. The embedding resin according to claim 1, which contains the filler in an amount of from 51% by weight to 74% by weight.

4. The embedding resin according to claim 1, wherein the filler contains at least one inorganic filler.

5. A wiring substrate comprising: an insulating
20 substrate having an opening; at least one electronic part disposed in the opening; and an embedding resin according to claim 1, wherein the at least one electronic part is embedded with the embedding resin.

